ALPHA & OMEGA SEMICONDUCTOR

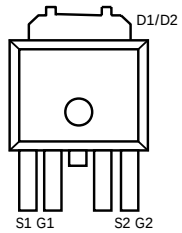
AOD608
Complementary Enhancement Mode Field Effect Transistor

General Description
The AOD608 uses advanced trench technology MOSFETs to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used in H-bridge, Inverters and other applications. *Standard product AOD608 is Pb-free (meets ROHS & Sony 259 specifications).*

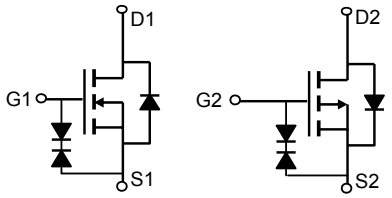
Features
n-channel	**p-channel**
V_{DS} (V) = 40V	-40V
I_D = 10A (V_{GS}=10V)	-10A (V_{GS} = -10V)
$R_{DS(ON)}$	$R_{DS(ON)}$
< 39 mΩ (V_{GS}=10V)	< 51 mΩ (V_{GS} = -10V)
< 50 mΩ (V_{GS}=4.5V)	< 75 mΩ (V_{GS} = -4.5V)

ESD rating: 3000V (HBM)

TO-252-4L
D-PAK



Top View
Drain Connected to Tab



n-channel **p-channel**

Absolute Maximum Ratings T_A=25°C unless otherwise noted

Parameter		**Symbol**	**Max n-channel**	**Max p-channel**	**Units**
Drain-Source Voltage		V_{DS}	40	-40	V
Gate-Source Voltage		V_{GS}	±20	±20	V
Continuous Drain Current [G]	T_C=25°C	I_D	10	-10	A
	T_C=100°C		10	-10	
Pulsed Drain Current [C]		I_{DM}	30	-30	
Avalanche Current [C]		I_{AR}	12	-15	A
Repetitive avalanche energy L=0.3mH [C]		E_{AR}	21	33	mJ
Power Dissipation [B]	T_C=25°C	P_D	20	50	W
	T_C=100°C		10	25	
Power Dissipation [A]	T_A=25°C	P_{DSM}	2	2.5	W
	T_A=70°C		1.3	1.6	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 175	-55 to 175	°C

Thermal Characteristics: n-channel and p-channel

Parameter		**Symbol**	**Device**	**Typ**	**Max**	
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	n-ch	19	23	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		n-ch	50	60	°C/W
Maximum Junction-to-Case [B]	Steady-State	$R_{\theta JC}$	n-ch	4	7.5	°C/W
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	p-ch	19	23	°C/W
Maximum Junction-to-Ambient [A]	Steady-State		p-ch	50	60	°C/W
Maximum Junction-to-Case [B]	Steady-State	$R_{\theta JC}$	p-ch	2.5	3	°C/W

N Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=250µA, V_{GS}=0V	40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=32V, V_{GS}=0V			1	µA
		T_J=55°C			5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V			1	mA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=250µA	1.5	2.2	3	V
$I_{D(ON)}$	On state drain current	V_{GS}=10V, V_{DS}=5V	30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V, I_D=10A		32	39	mΩ
		T_J=125°C		45		
		V_{GS}=4.5V, I_D=4A		42	50	mΩ
g_{FS}	Forward Transconductance	V_{DS}=5V, I_D=10A		13		S
V_{SD}	Diode Forward Voltage	I_S=1A,V_{GS}=0V		0.75	1	V
I_S	Maximum Body-Diode Continuous Current				3.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=30V, f=1MHz		500		pF
C_{oss}	Output Capacitance			106		pF
C_{rss}	Reverse Transfer Capacitance			38		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		2.6		Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=10V, V_{DS}=20V, I_D=10A		8.4		nC
Q_g(4.5V)	Total Gate Charge			4.1		nC
Q_{gs}	Gate Source Charge			1.6		nC
Q_{gd}	Gate Drain Charge			2.6		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=10V, V_{DS}=20V, R_L=2Ω, R_{GEN}=3Ω		4.8		ns
t_r	Turn-On Rise Time			2		ns
$t_{D(off)}$	Turn-Off DelayTime			17		ns
t_f	Turn-Off Fall Time			2.1		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=10A, dI/dt=100A/µs		17.5		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=10A, dI/dt=100A/µs		11.1		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C.

G. The maximum current rating is limited by bond-wires.

H. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

Rev0: Aug 2006

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

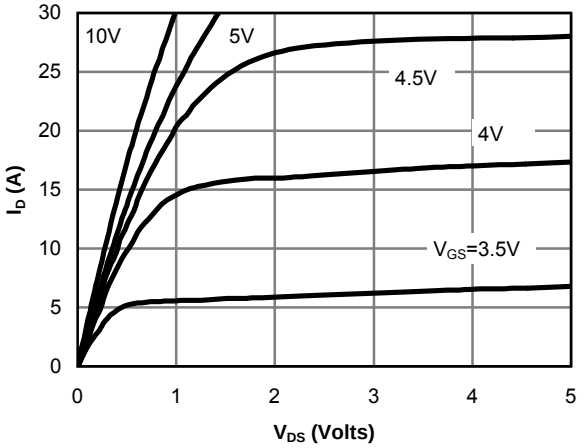


Fig 1: On-Region Characteristics

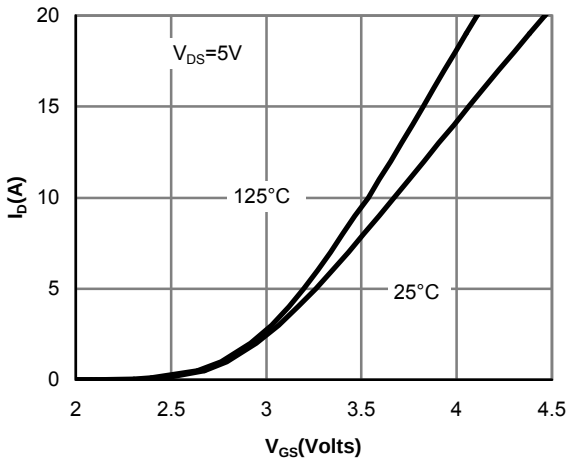


Figure 2: Transfer Characteristics

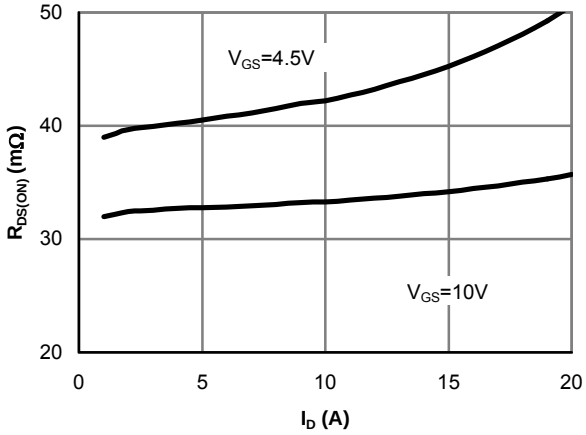


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

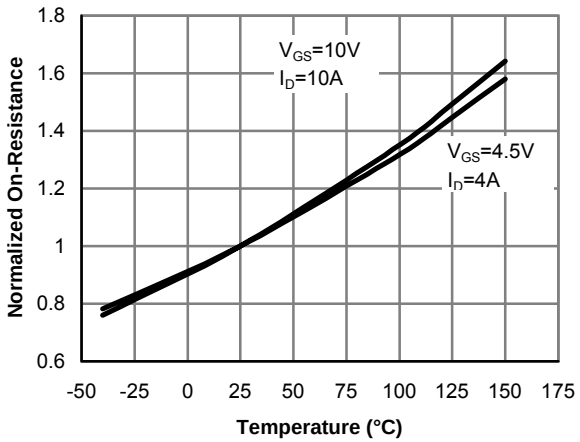


Figure 4: On-Resistance vs. Junction Temperature

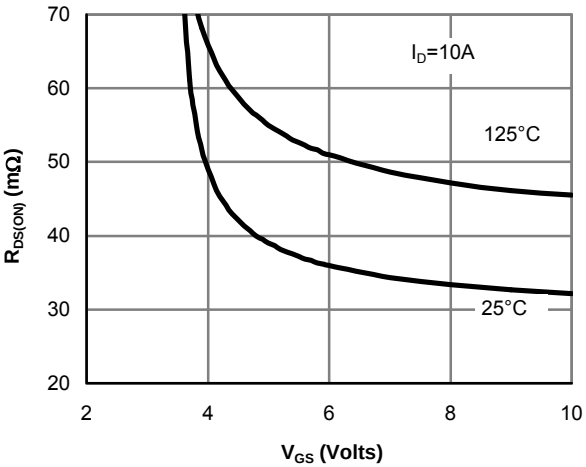


Figure 5: On-Resistance vs. Gate-Source Voltage

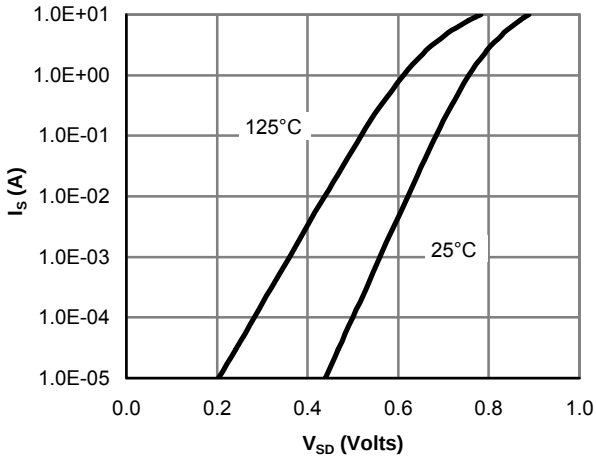


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

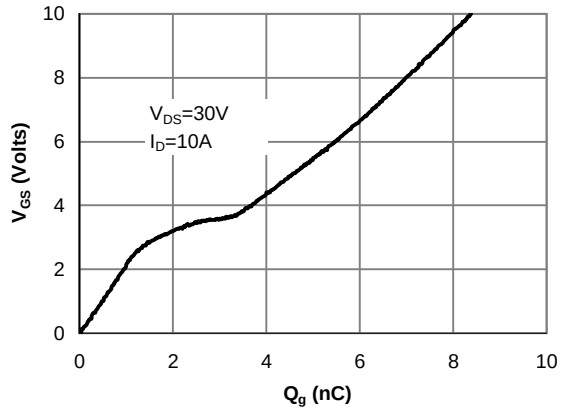


Figure 7: Gate-Charge Characteristics

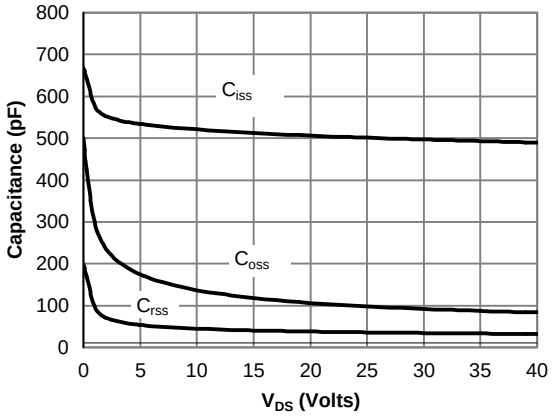


Figure 8: Capacitance Characteristics

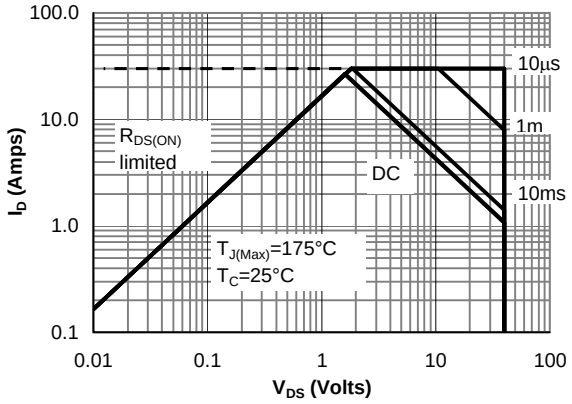


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

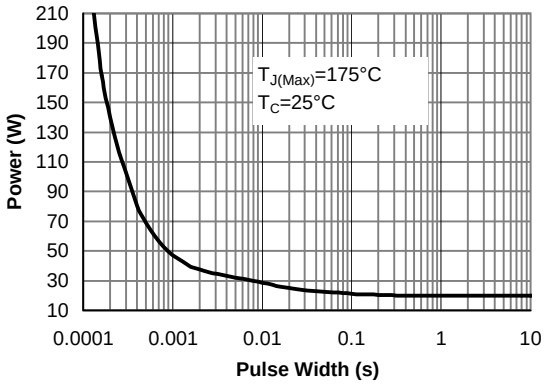


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

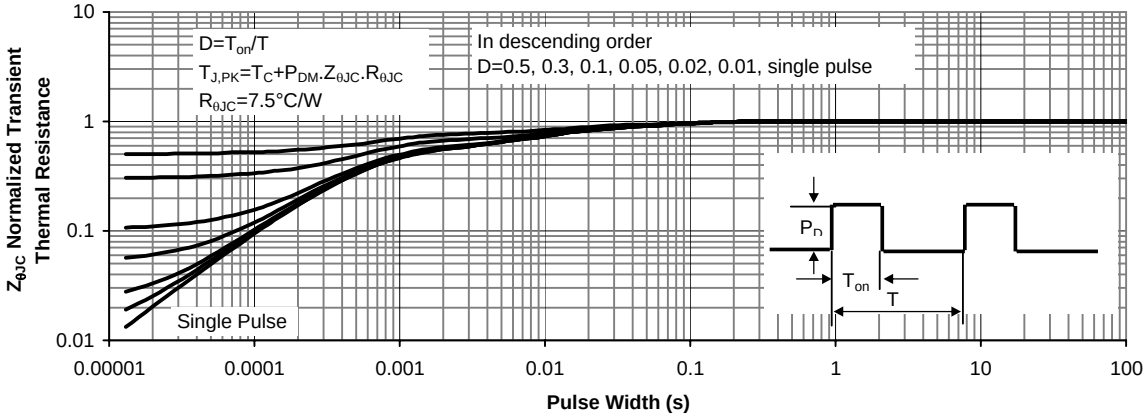


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: N-CHANNEL

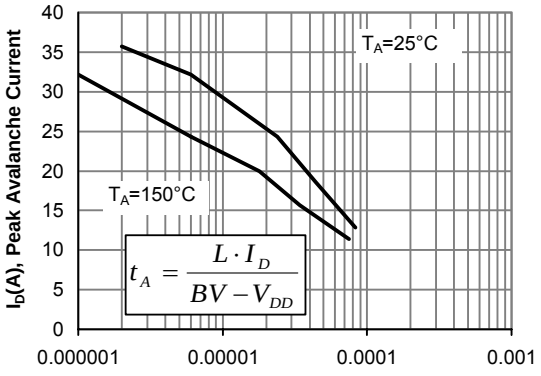


Figure 12: Single Pulse Avalanche capability

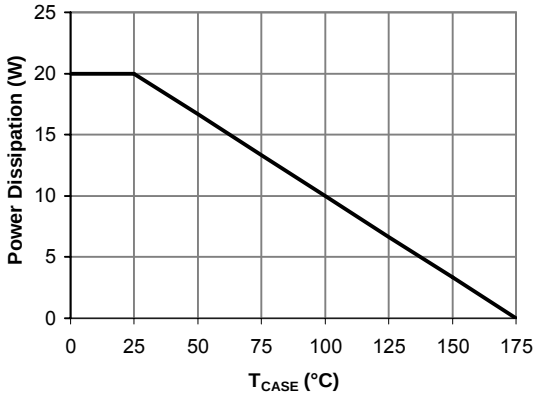


Figure 13: Power De-rating (Note B)

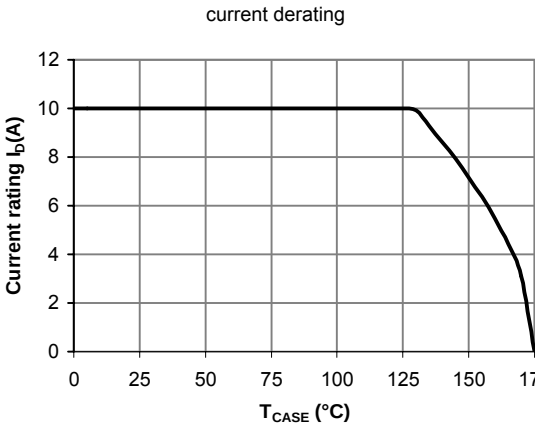


Figure 14: Current De-rating (Note B)

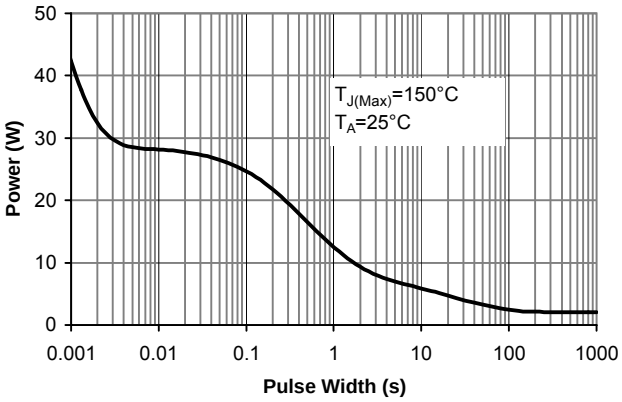


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

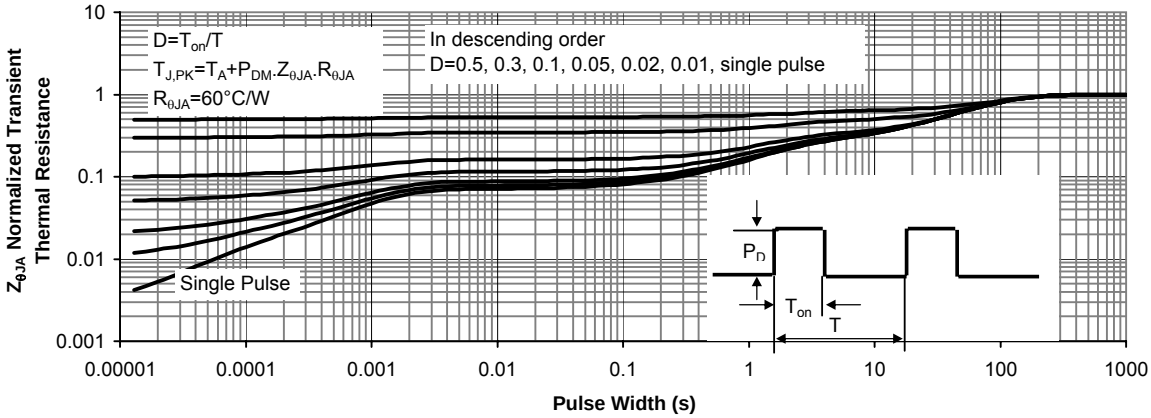


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

P-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250µA, V_{GS}=0V	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-32V, V_{GS}=0V			-1	µA
		T_J=55°C			-5	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}=±20V			±150	µA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250µA	-1.5	-1.9	-3	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS}=-5V	-30			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-10A		42	51	mΩ
		T_J=125°C		59		
		V_{GS}=-4.5V, I_D=-4A		62	75	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-10A		13		S
V_{SD}	Diode Forward Voltage	I_S=-1A,V_{GS}=0V		-0.75	-1	V
I_S	Maximum Body-Diode Continuous Current				3.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-20V, f=1MHz		1000		pF
C_{oss}	Output Capacitance			152		pF
C_{rss}	Reverse Transfer Capacitance			77		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz		11		Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge (10V)	V_{GS}=-10V, V_{DS}=-20V, I_D=-10A		17.4		nC
Q_g(4.5V)	Total Gate Charge (4.5V)			8.8		nC
Q_{gs}	Gate Source Charge			3.3		nC
Q_{gd}	Gate Drain Charge			4.5		nC
$t_{D(on)}$	Turn-On DelayTime	V_{GS}=-10V, V_{DS}=-20V, R_L=2Ω, R_{GEN}=3Ω		9.7		ns
t_r	Turn-On Rise Time			6.3		ns
$t_{D(off)}$	Turn-Off DelayTime			35.5		ns
t_f	Turn-Off Fall Time			26		ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-10A, dI/dt=100A/µs		22		ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-10A, dI/dt=100A/µs		15.9		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B. The power dissipation P_D is based on $T_{J(MAX)}$=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=175°C.

D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=175°C.

G. The maximum current rating is limited by bond-wires.

H. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

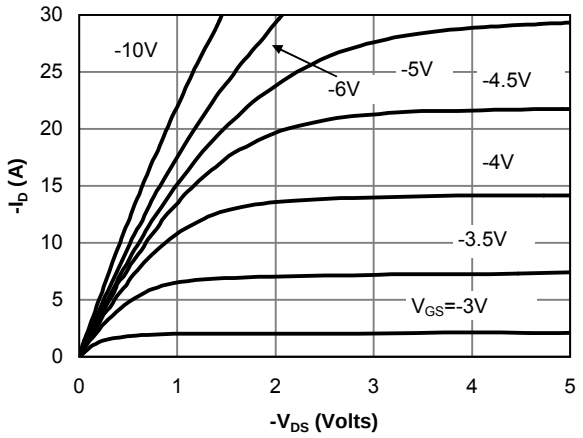

Fig 1: On-Region Characteristics

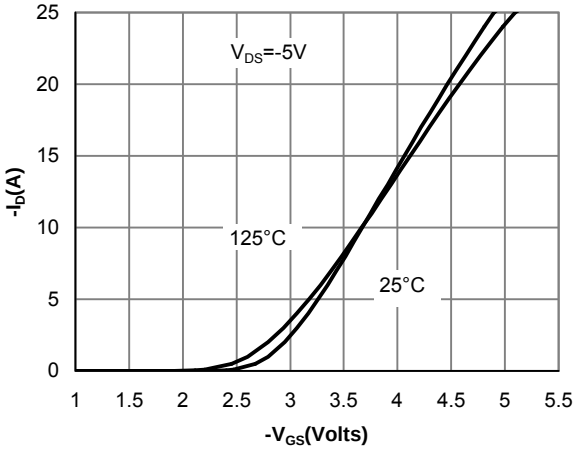

Figure 2: Transfer Characteristics

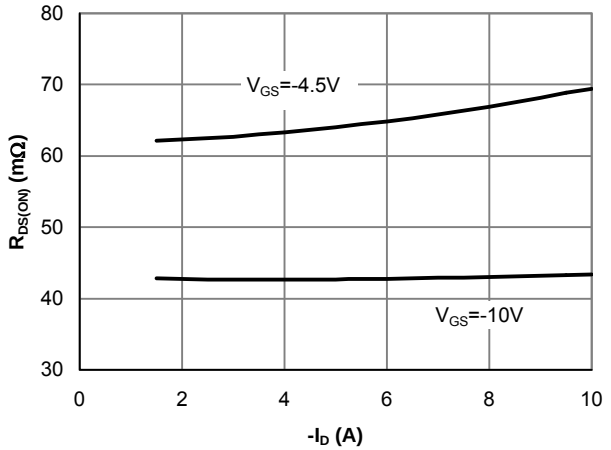

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

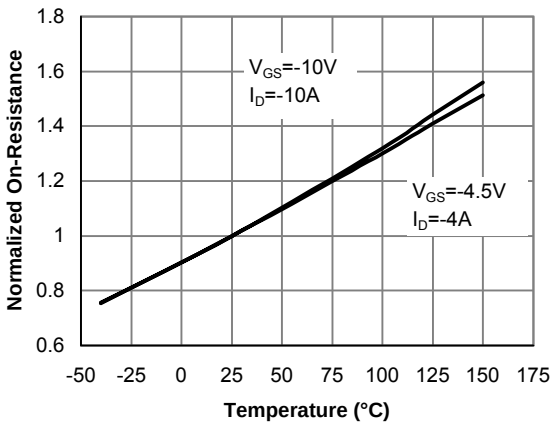

Figure 4: On-Resistance vs. Junction Temperature

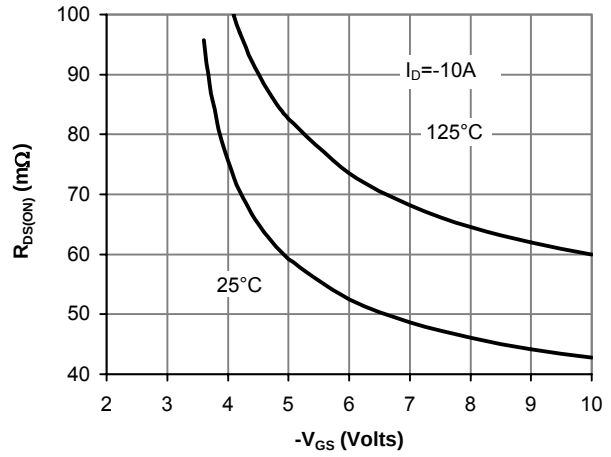

Figure 5: On-Resistance vs. Gate-Source Voltage

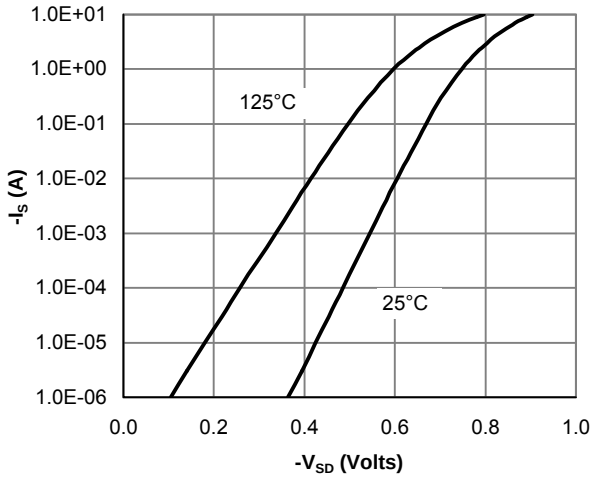

Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

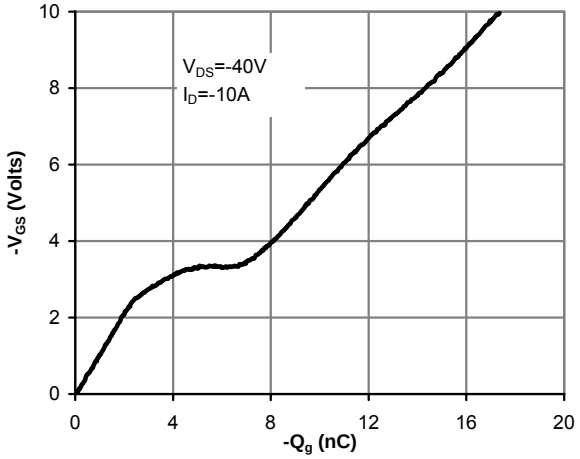

Figure 7: Gate-Charge Characteristics

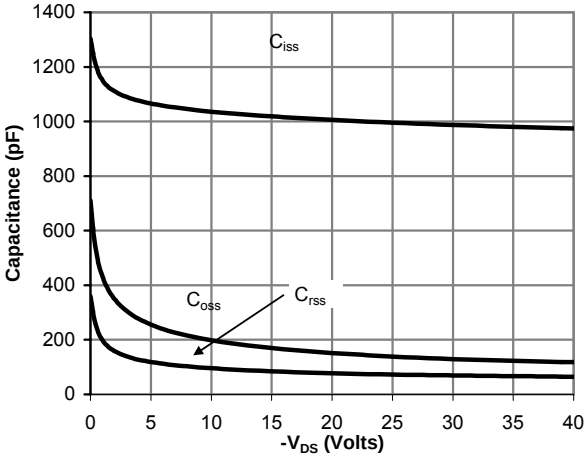

Figure 8: Capacitance Characteristics

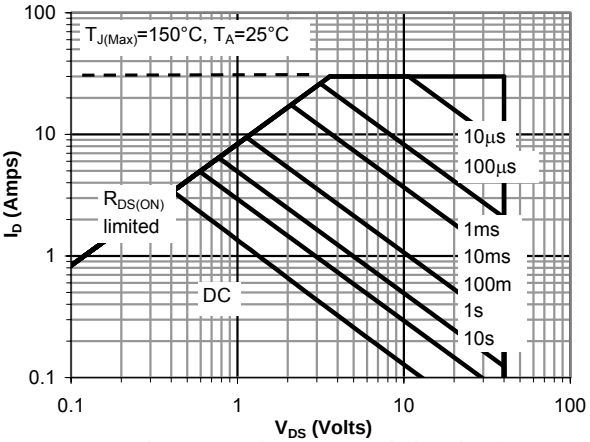

Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

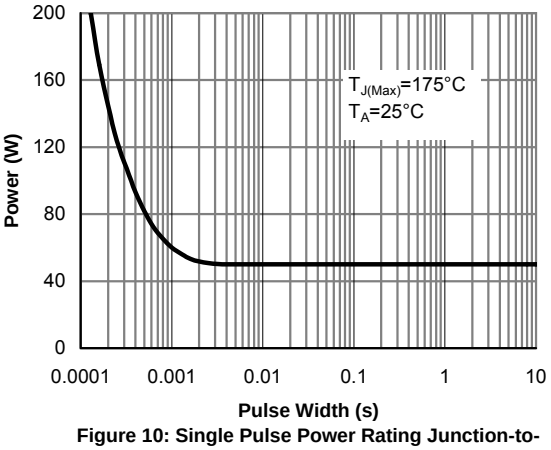

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

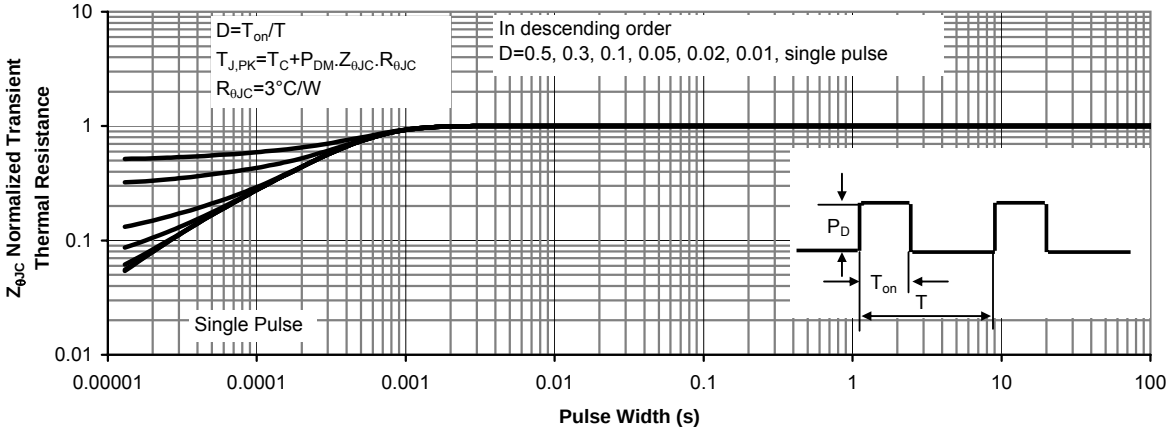

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL

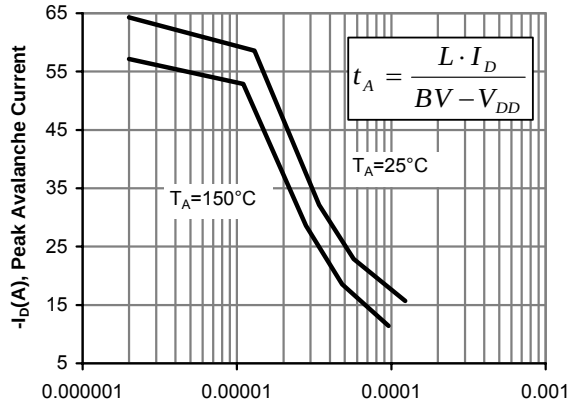

Figure 12: Single Pulse Avalanche capability

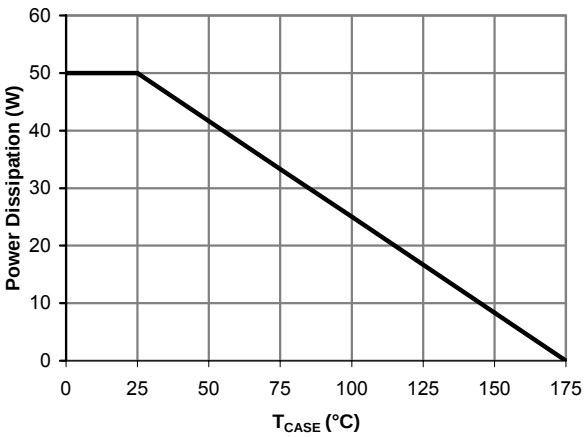

Figure 13: Power De-rating (Note B)

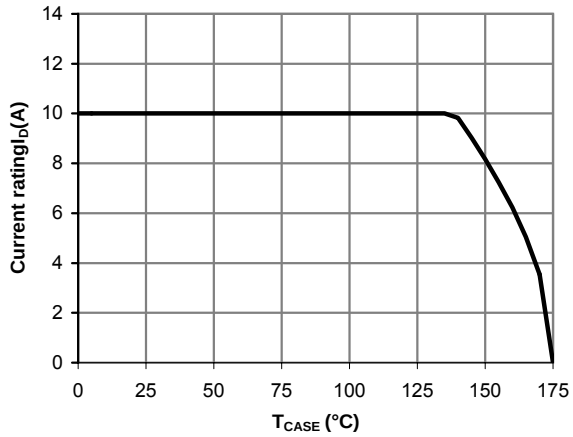

Figure 14: Current De-rating (Note B)

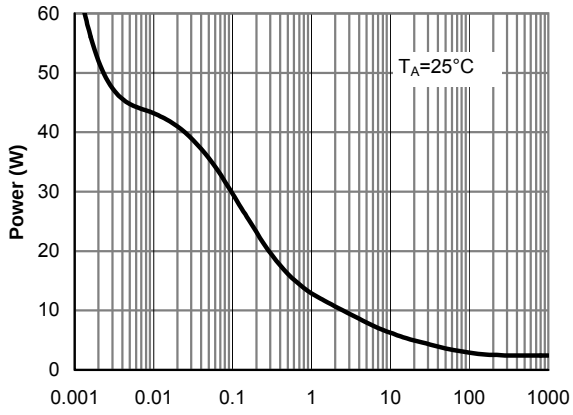

Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

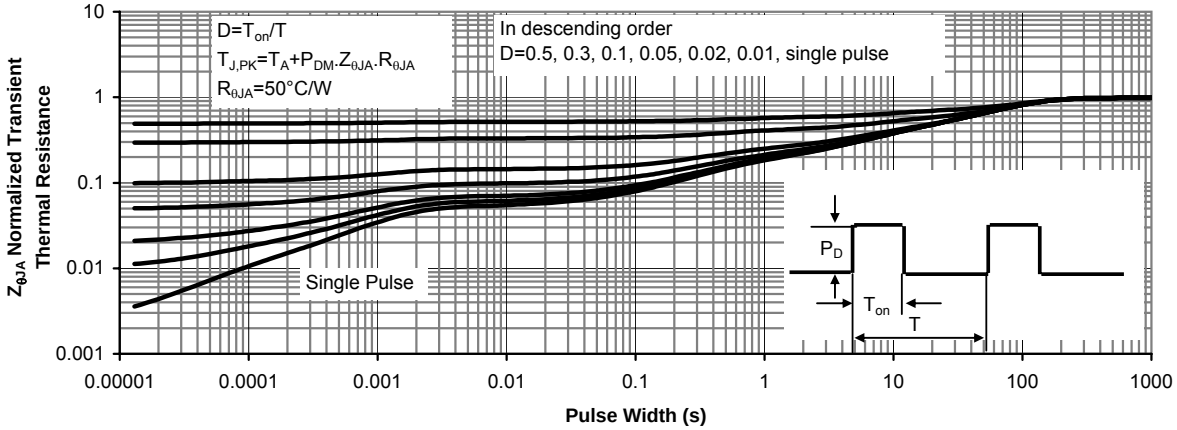

Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)